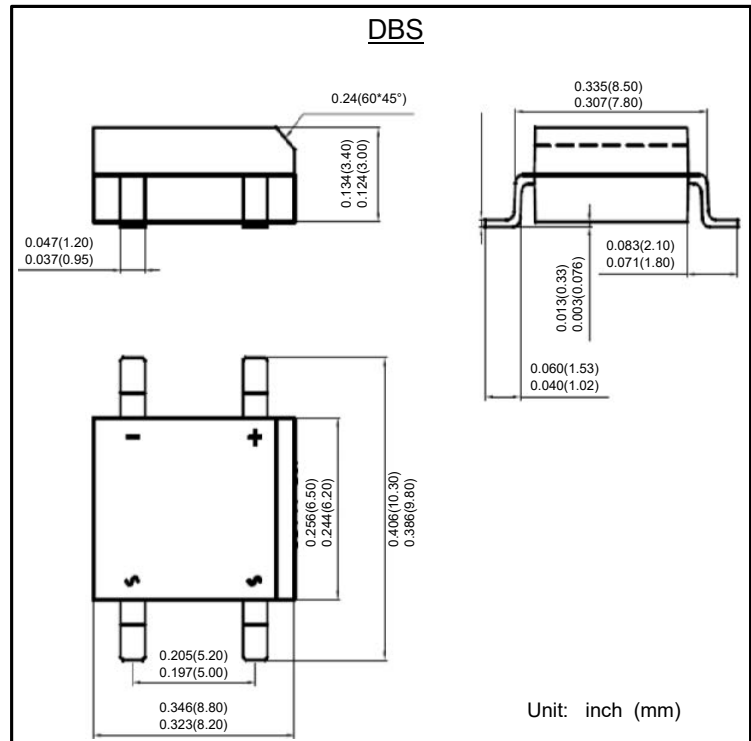


### Features

- Low reverse leakage
- High forward surge capability
- High temperature soldering guaranteed:  
260°C/10seconds
- Glass passivated chip
- Lead and body according with RoHS standard

### Mechanical Data

- Case: DBS Molded plastic
- Polarity: Symbols molded or marked on body
- Mounting Position: Any



### Maximum Ratings & Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbols	DB 201S	DB 202S	DB 203S	DB 204S	DB 205S	DB 206S	DB 207S	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	2.0							A
Non-repetitive peak forward surge current 10 ms singlehalf sine-wave	$I_{FSM}$	60							A
@ $I_F=1.0A$ Maximum forward voltage	$V_F$	1.10							V
@ $V_{DC}$ Maximum reverse current	$I_R$	5							μA
		100							
Typical thermal resistance (Note 1)	$R_{\theta JA}$	40							°C/W
$V_R=4.0V, f=1MHz$ Type junction capacitance	$C_j$	30							pF
Operating junction and storage temperature rang	$T_j, T_{STG}$	-55 --- +150							°C

Note:

1) Thermal resistance from junction to ambient, PCB mounted.

## Characteristic Curves

